

Title (en)  
HOUSING AND METHOD FOR PRODUCING A HOUSING

Title (de)  
GEHÄUSE UND VERFAHREN ZUM HERSTELLEN EINES GEHÄUSES

Title (fr)  
BOÎTIER ET PROCÉDÉ DE FABRICATION D'UN BOÎTIER

Publication  
**EP 2619860 A1 20130731 (DE)**

Application  
**EP 11760448 A 20110913**

Priority  
• DE 102010046088 A 20100920  
• EP 2011065842 W 20110913

Abstract (en)  
[origin: WO2012038303A1] The invention relates to a housing (1) for an optoelectronic semiconductor component (10), comprising a housing body (2) having a mounting plane (20) and a lead frame (3) with a first connecting lead (31) and a second connecting lead (32). The housing body (2) deforms the lead frame (3) in some regions. The lead frame (3) has a main extension plane which extends obliquely or perpendicularly with respect to the mounting plane (20). The invention further relates to a semiconductor component (10) having such a housing (10) and a semiconductor chip (6) and to a method for producing a housing (1).

IPC 8 full level  
**H01S 5/0232** (2021.01); **H01L 33/48** (2010.01); **H01L 33/62** (2010.01); **H01S 5/02375** (2021.01); **H01S 5/024** (2006.01)

CPC (source: EP US)  
**H01L 23/495** (2013.01 - EP US); **H01S 5/02208** (2013.01 - US); **H01S 5/0231** (2021.01 - EP US); **H01S 5/0232** (2021.01 - EP US); **H01S 5/02345** (2021.01 - EP US); **H01S 5/02375** (2021.01 - EP US); **H01S 5/024** (2013.01 - EP US); **H05K 5/0091** (2013.01 - US); **H01L 33/62** (2013.01 - EP US); **H01L 2224/48091** (2013.01 - EP US); **H01L 2224/48465** (2013.01 - EP US); **H01S 5/02216** (2013.01 - EP US); **H01S 5/02253** (2021.01 - EP US); **H01S 5/02257** (2021.01 - EP US); **H01S 5/02476** (2013.01 - EP US)

Citation (search report)  
See references of WO 2012038303A1

Designated contracting state (EPC)  
AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

DOCDB simple family (publication)  
**DE 102010046088 A1 20120322**; CN 103119806 A 20130522; CN 103119806 B 20160518; EP 2619860 A1 20130731; US 2013266035 A1 20131010; US 2016036198 A1 20160204; US 9178332 B2 20151103; US 9461438 B2 20161004; WO 2012038303 A1 20120329

DOCDB simple family (application)  
**DE 102010046088 A 20100920**; CN 201180045253 A 20110913; EP 11760448 A 20110913; EP 2011065842 W 20110913; US 201113825290 A 20110913; US 201514884500 A 20151015